



Product Change Notification - KSRA-31AOHM485

Date:

27 Apr 2018

Product Category:

Memory; Others; Temperature Sensors

Affected CPNs:**Notification subject:**

CCB 2953 Final Notice: Qualification of matte tin lead finish for selected Atmel products available in 8L SOIC at ASSH Assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of matte tin lead finish for selected Atmel products available in 8L SOIC at ASSH Assembly site.

Pre Change:

Assembled at ANAP Assembly site using 8290 die attach material, and G700 molding compound material and NiPdAu lead finish or ASSH Assembly site using EN 4900G die attach material, G700 molding compound material and NiPdAu lead finish.

Post Change:

Assembled at ANAP Assembly site using 8290 die attach material, and G700 molding compound material and NiPdAu lead finish or ASSH Assembly site using EN 4900G die attach material, CEL-9240HF10AK molding compound material and Matte Tin lead finish

Pre and Post Change Summary:

Assembly Site	Pre Change		Post Change	
	ANAP Assembly Site	ASSH Assembly Site	ANAP Assembly Site	ASSH Assembly Site
Wire material	CuPdAu Wire	CuPdAu Wire	CuPdAu Wire	CuPdAu Wire
Die attach material	8290	EN 4900G	8290	EN 4900G
Molding compound material	G700	G700	G700	CEL-9240HF10AK
Lead frame material	C194	C194	C194	C194
Lead Finish	NiPdAu	NiPdAu	NiPdAu	Matte Tin

Impacts to Data Sheet:

None

Change Impact:

None



Reason for Change:

To improve manufacturability by qualifying new bill of material for ASSH assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 27, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	June 2017					-->	April 2018				May 2018				
Workweek	22	23	24	25	26		14	15	16	17	18	19	20	21	22
Initial PCN Issue Date		X													
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date														X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

June 15, 2017: Issued initial notification.

June 20, 2017: Re-issued initial notification to include affected parts list and qualification plan.

June 23, 2017: Re-issued initial notification to correct a typo on molding compound material from CEL-9240HF10AK and G700A/G700LS to G700.

July 13, 2017: Re-issued initial notification to include ANAP Assembly site in the post change.

April 27, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on May 27, 2018.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-31AOHM485_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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